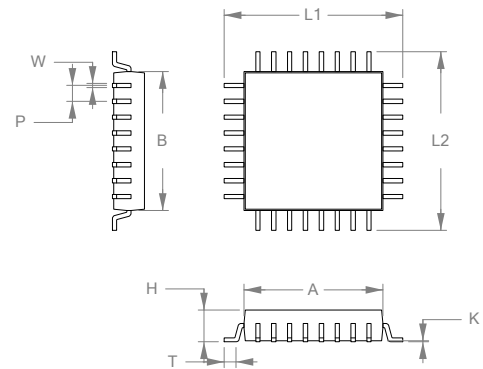


Component (Fig. 1)

Quad Flat Pack (QFP)
Pitch.....0.80
Pins A.....8
Pins B.....8
Pin Count.....32
L1min.....8.60
L1max.....9.40
L2min.....8.60
L2max.....9.40
Tmin.....0.45
Tmax.....0.75
Wmin.....0.17
Wmax.....0.27
Amin.....6.80
Amax.....7.20
Bmin.....6.80
Bmax.....7.20
Hmax.....1.60
Kmin.....0.05

Fig.1

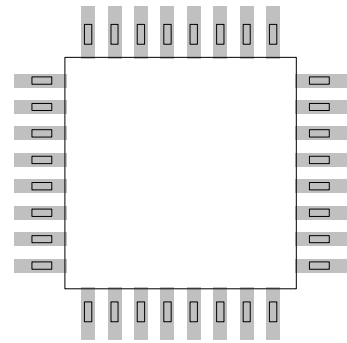


Solder Joint Goals (Fig. 2)

Environment is B - NOMINAL

Toe (Outside) Goal.....0.35
Toe min.....0.34
Toe max.....0.75
Heel (Inside) Goal.....0.35
Heel Min.....0.22
Heel max.....0.68
Side Goal.....0.03
Side Min.....0.03
Side max.....0.12

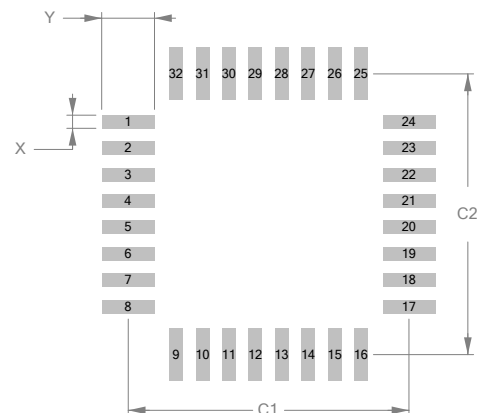
Fig.2



Land Pattern (Fig. 3)

Pitch.....0.80
C1.....8.50
Y.....1.60
X.....0.40
C2.....8.50

Fig.3



Silkscreen (Fig. 4)

R1.....6.25
R2.....6.25

Assembly (Fig. 5)

Anom.....7.00
Bnom.....7.00

Courtyard (Fig. 6)

V1.....10.60
V2.....10.60

Program Version: 2009.19.02

Advisories

Land is being trimmed for
lands that extend under the
body.

Fig.4

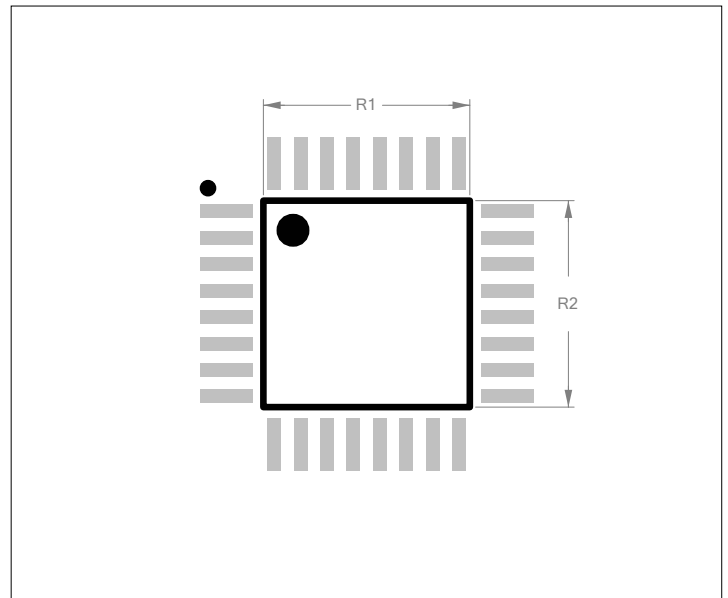


Fig.5

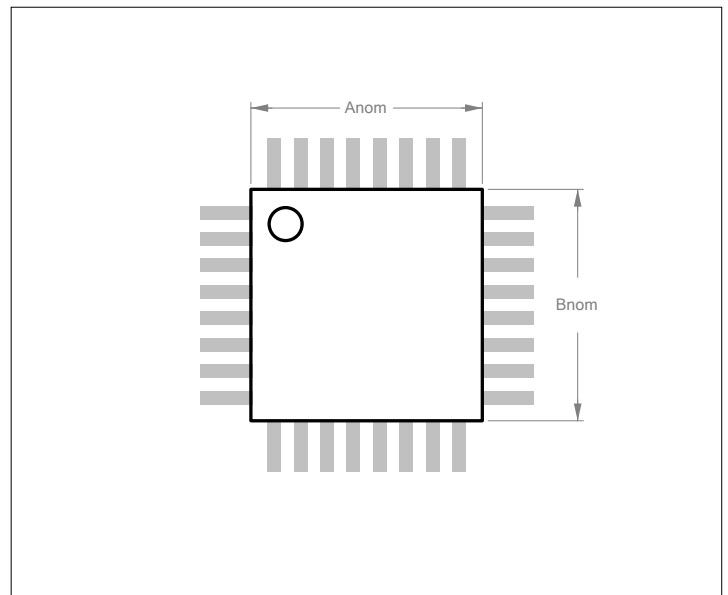


Fig.6

